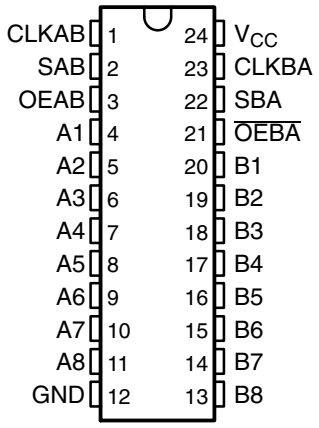
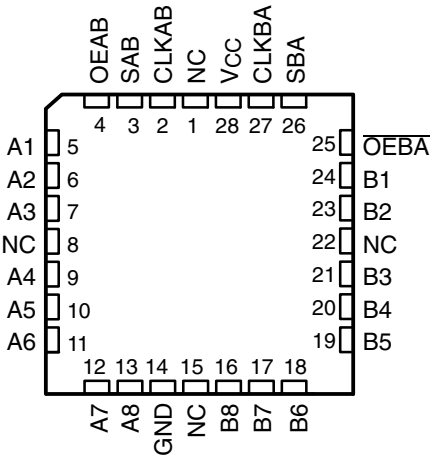
- **State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Independent Registers and Enables for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- **Power-Up High-Impedance Mode**
- **Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (JT, NT)**

SN54BCT652 . . . JT OR W PACKAGE
SN74BCT652 . . . DW OR NT PACKAGE
(TOP VIEW)



SN54BCT652 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

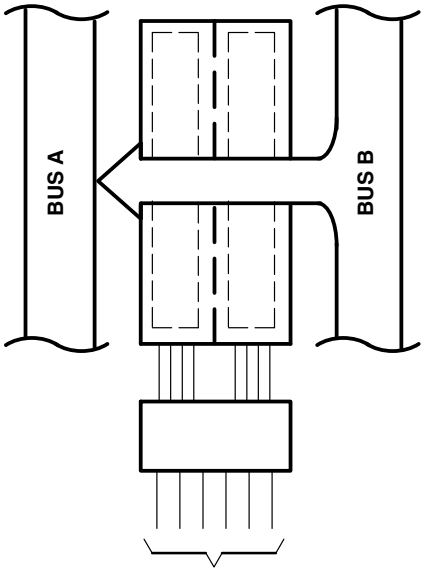
description

These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.

Output-enable (OEAB and $\overline{\text{OEBA}}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the ′BCT652.

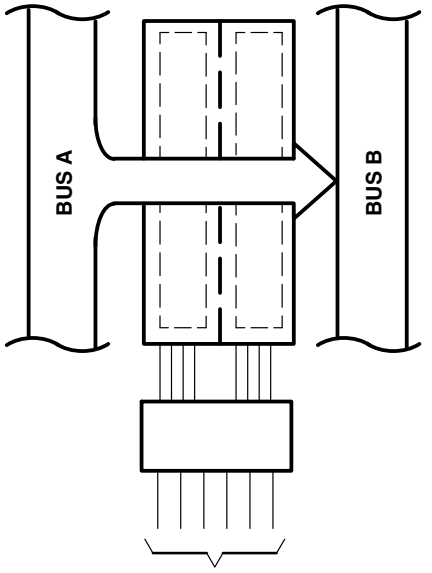
Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. In this configuration each output reinforces its input. Therefore, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remain at its last state.

The SN54BCT652 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74BCT652 is characterized for operation from 0°C to 70°C.



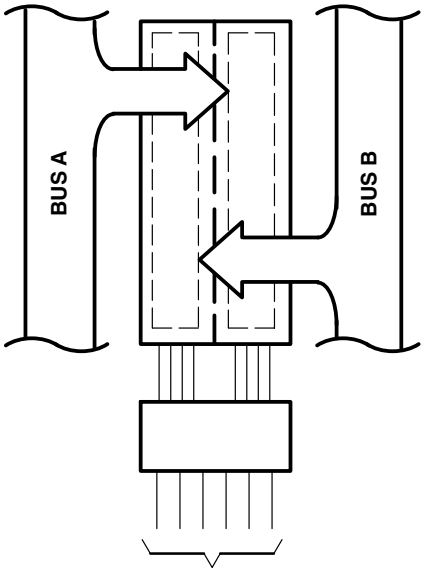
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO BUS A



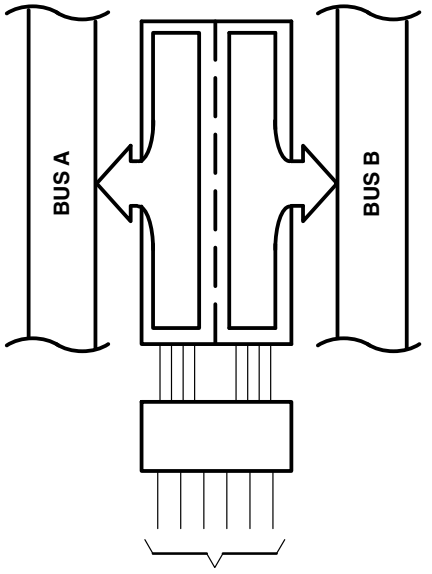
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER
BUS A TO BUS B



3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B



3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	L	L	H	H
L	L	X	L	X	H
H	H	L	X	H	X

TRANSFER STORED DATA
TO A AND/OR B

Figure 1. Bus-Management Functions

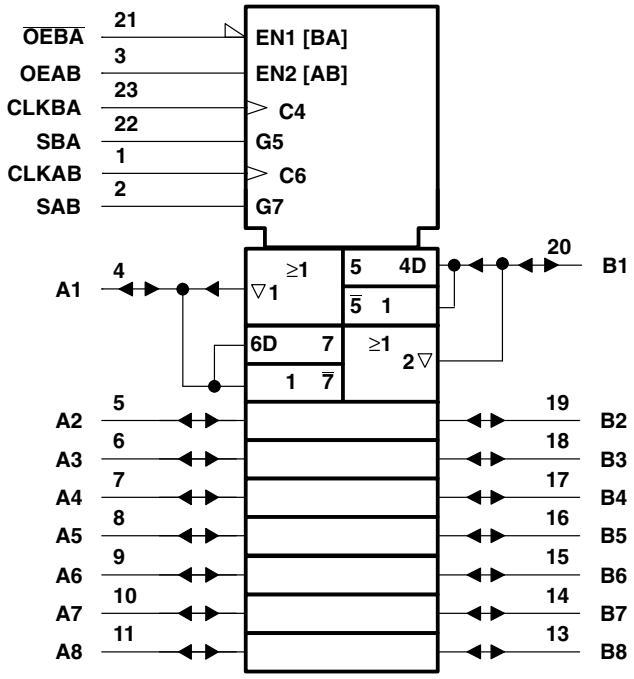
Pin numbers shown are for the DW, JT, NT, and W packages.

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

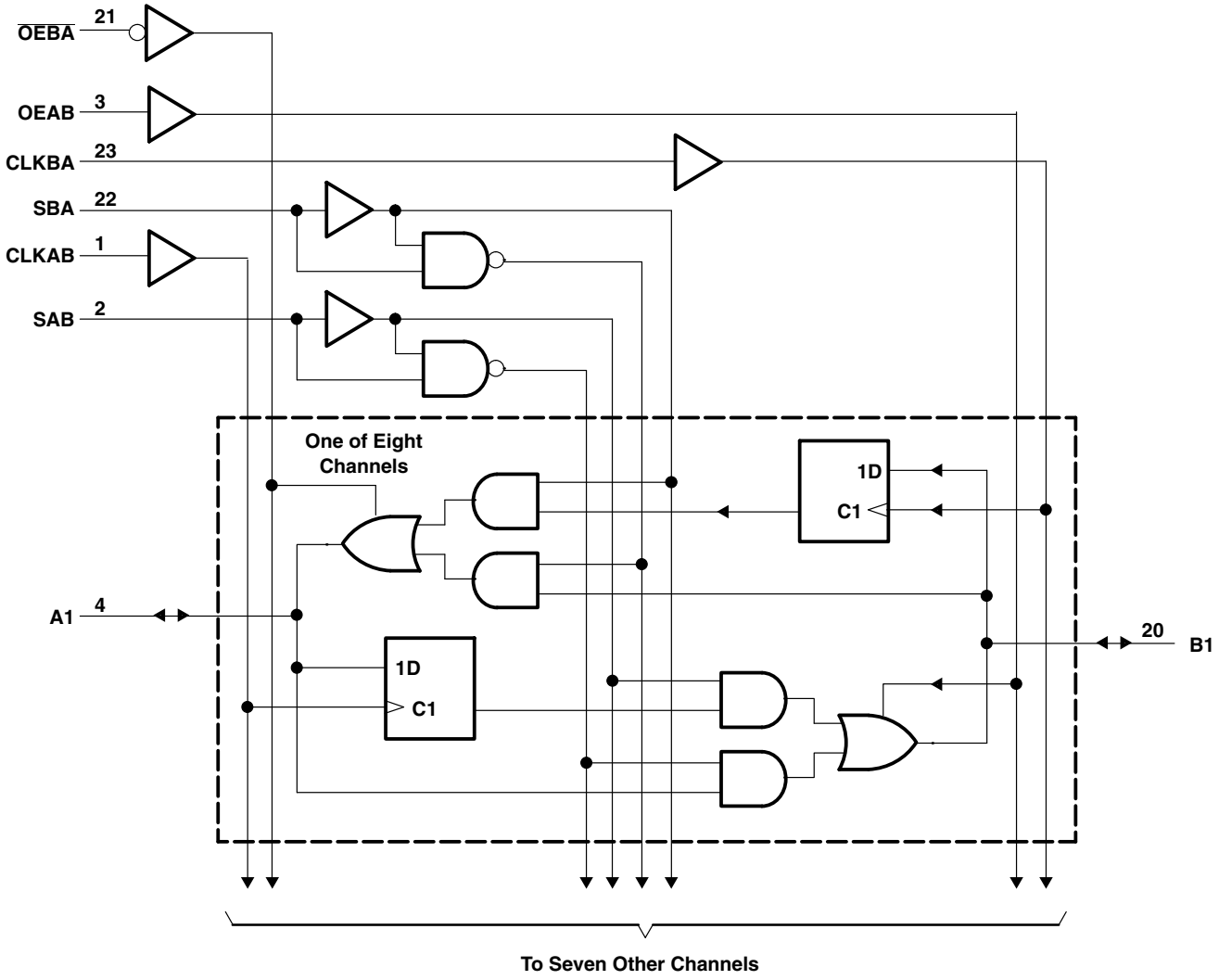
† The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or $\overline{OEBA}$ inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.
‡ Select control = L; clocks can occur simultaneously.
Select control = H; clocks must be staggered in order to load both registers.

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . – 0.5 V to 7 V
Input voltage range: Control inputs (see Note 1) . . . . . – 0.5 V to 7 V
I/O ports (see Note 1) . . . . . – 0.5 V to 5.5 V
Voltage range applied to any output in the disabled or power-off state, V_O . . . . . – 0.5 V to 7 V
Voltage range applied to any output in the high state, V_O . . . . . – 0.5 V to V_{CC}
Current into any output in the low state: SN54BCT652 . . . . . 96 mA
SN74BCT652 . . . . . 128 mA
Operating free-air temperature range: SN54BCT652 . . . . . – 55°C to 125°C
SN74BCT652 . . . . . 0°C to 70°C
Storage temperature range . . . . . – 65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		SN54BCT652			SN74BCT652			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			–18			–18	mA
I_{OH}	High-level output current			–12			–15	mA
I_{OL}	Low-level output current			48			64	mA
T_A	Operating free-air temperature	–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54BCT652			SN74BCT652			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4	3.3		2.4	3.3		V
			I_{OH} = –12 mA	2	3.2					
			I_{OH} = –15 mA				2	3.1		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA		0.38	0.55				V
			I_{OL} = 64 mA					0.42	0.55	
I_I	A or B port	V_{CC} = 5.5 V,	V_I = 5.5 V			1			1	mA
	Control inputs					1			1	
I_{IH}‡	A or B port	V_{CC} = 5.5 V,	V_I = 2.7 V			70			70	µA
	Control inputs					20			20	
I_{IL}‡	A or B port	V_{CC} = 5.5 V,	V_I = 0.5 V			–0.7			–0.7	mA
	Control inputs					–0.7			–0.7	
I_{OS}§		V_{CC} = 5.5 V,	V_O = 0	–100		–225	–100		–225	mA
I_{CCL}	A or B port	V_{CC} = 5.5 V,	V_I = 0		43	69		43	69	mA
I_{CCH}	A or B port	V_{CC} = 5.5 V,	V_I = 4.5 V		6	10		6	10	mA
I_{CCZ}	A or B port	V_{CC} = 5.5 V,	V_I = 0		10	17		10	17	mA
C_i	Control inputs	V_{CC} = 5 V,	V_I = 2.5 V or 0.5 V		6			6		pF
C_{io}	A or B port	V_{CC} = 5 V,	V_O = 2.5 V or 0.5 V		14			14		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V_{CC} = 5 V, T_A = 25°C		SN54BCT652		SN7BCTT652		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	77	0	77	0	77	MHz
t_w	Pulse duration, CLK high or low	6.5		7		6.5		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	5		6		5		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	1		1		1		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54BCT652		SN74BCT652		UNIT
			MIN	TYP	MIN	MIN	MAX	MIN	MAX	
f_{max}			77			77		77		MHz
t_{PLH}	CLKBA	A	2.6	6.9	8.9	2.6	11.6	2.6	10.5	ns
t_{PHL}			2.8	6.8	8.8	2.8	10.7	2.8	9.9	
t_{PLH}	CLKAB	B	2.6	6.9	8.9	2.6	11.6	2.6	10.5	ns
t_{PHL}			2.8	6.8	8.8	2.8	10.7	2.8	9.9	
t_{PLH}	A	B	1.7	5.8	7.5	1.7	10.3	1.7	8.9	ns
t_{PHL}			2.4	6.5	8.2	2.4	11	2.4	9.8	
t_{PLH}	B	A	1.7	5.8	7.5	1.7	10.3	1.7	8.9	ns
t_{PHL}			2.4	6.5	8.2	2.4	11	2.4	9.8	
t_{PLH}	SBA† (with B high)	A	3.5	8.8	10.8	3.5	14.2	3.5	13.1	ns
t_{PHL}			2.4	5.9	7.7	2.4	9.1	2.4	8.5	
t_{PLH}	SBA† (with B low)	A	3	7.6	9.7	3	12.4	3	11.3	ns
t_{PHL}			3.8	8.3	10.4	3.8	12.9	3.8	12.5	
t_{PLH}	SAB† (with A high)	B	3.5	8.8	10.8	3.5	14.2	3.5	13.1	ns
t_{PHL}			2.4	5.9	7.7	2.4	9.1	2.4	8.5	
t_{PLH}	SAB† (with A low)	B	3	7.6	9.7	3	12.4	3	11.3	ns
t_{PHL}			3.8	8.3	10.4	3.8	12.9	3.8	12.5	
t_{PZH}	$\overline{OEBA}$	A	2.5	7.2	8.9	2.5	11.2	2.5	10.6	ns
t_{PZL}			3.2	8.1	10.1	3.2	12.6	3.2	12	
t_{PHZ}	$\overline{OEBA}$	A	2.8	6.7	8.6	2.8	10.9	2.8	10	ns
t_{PLZ}			2.4	6.3	8.4	2.4	10.5	2.4	9.5	
t_{PZH}	OEAB	B	1.5	5.4	7.1	1.5	9	1.5	8.1	ns
t_{PZL}			2.3	6.2	8.1	2.3	10.3	2.3	9.3	
t_{PHZ}	OEAB	B	3.5	8.2	10	3.5	12.2	3.5	11.6	ns
t_{PLZ}			2.8	7.2	9.5	2.8	12	2.8	11.3	

† These parameters are measured with the internal output state of the storage register opposite to that of the bus input.
NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74BCT652DW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT652	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

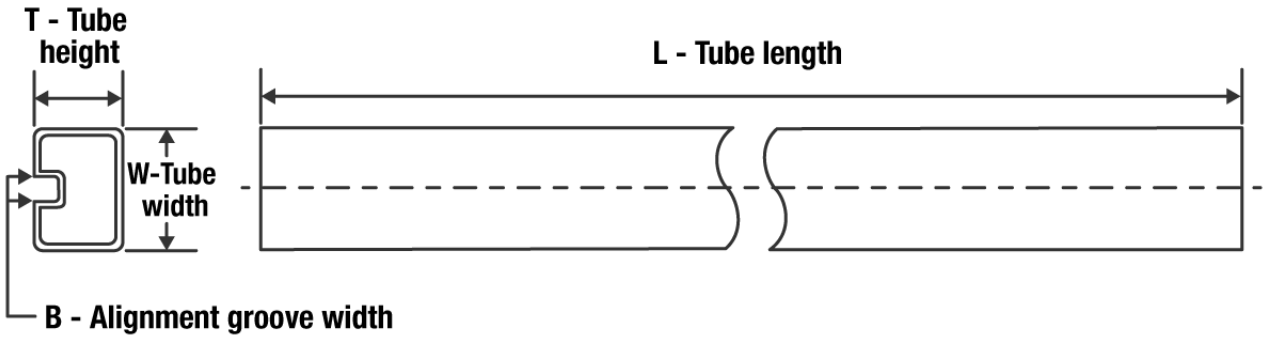
OTHER QUALIFIED VERSIONS OF SN54BCT652, SN74BCT652 :

- Catalog: SN74BCT652
- Military: SN54BCT652

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

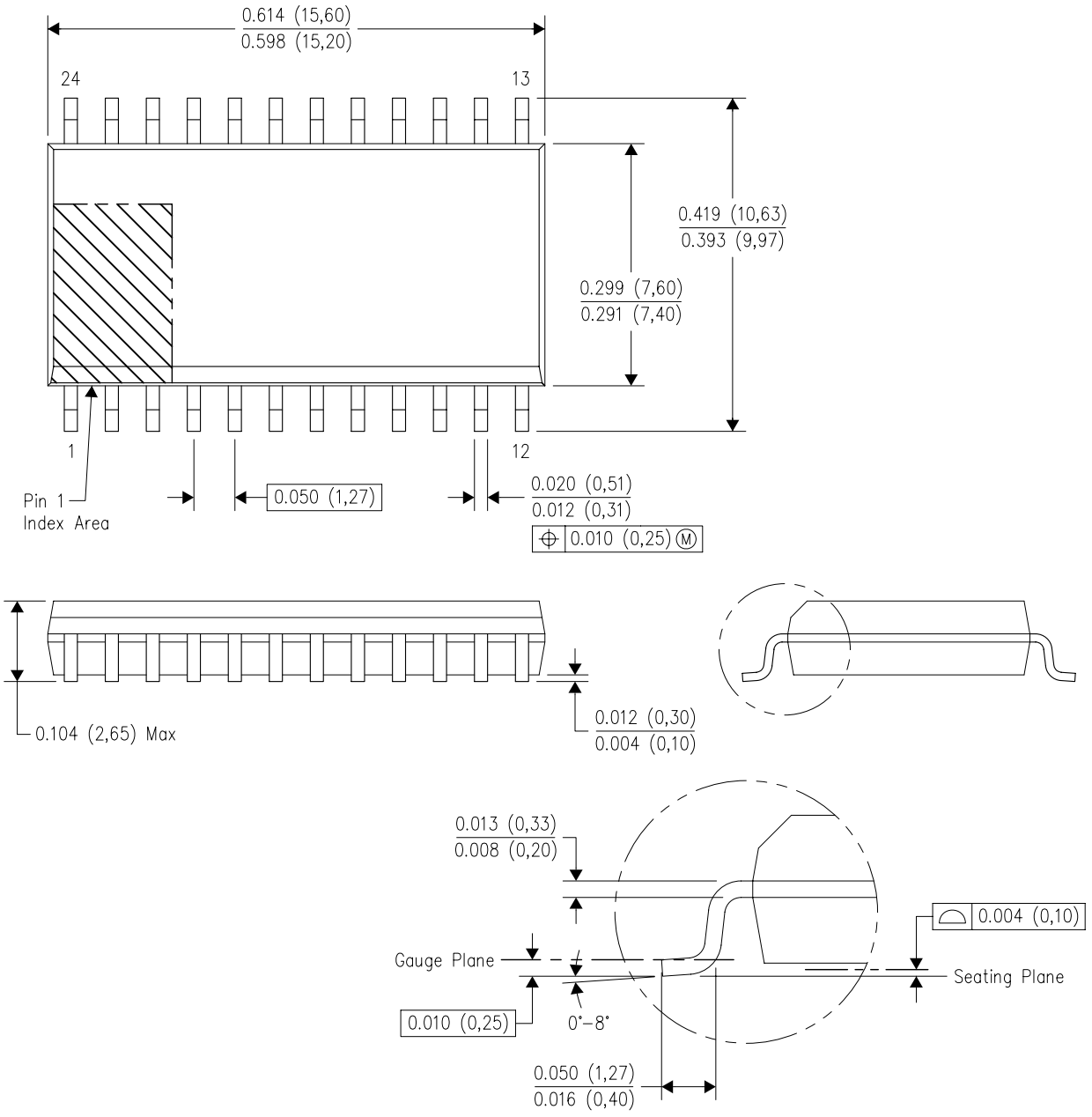
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74BCT652DW	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

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